VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Three Times Amended) A semiconductor device, comprising:

a semiconductor chip;

a single dielectric layer;

electrically conductive leads on said dielectric layer; and

a low temperature curing adhesive material that cures to about ninety percent of its maximum strength within two to three hours without exceeding one hundred fifty degrees Fahrenheit, said low temperature curing adhesive material being located between said semiconductor chip and said dielectric layer.

10. (Three Times Amended) A taped semiconductor product, comprising:

integrated circuits formed in semiconductor material;

a tape having openings aligned with said integrated circuits, wherein said tape includes a single dielectric layer and electrically conductive leads, said leads being printed on said single dielectric layer;

bond wires extending through said openings, said bond wires being electrically connected to said integrated circuits; and

adhesive material between said tape and said integrated circuits, wherein said adhesive material cures to about ninety percent of its maximum strength within twenty four to thirty six hours at room temperature.

13. (Three Times Amended) A tape for manufacturing semiconductor devices, said tape comprising:

a single dielectric layer having openings;

electrically conductive leads associated with said openings, said leads being printed on said dielectric layer; and

a low temperature curing adhesive material that cures to about ninety percent of its maximum strength within two to three hours without exceeding one hundred fifty degrees Fahrenheit, said low temperature curing adhesive material being located between said semiconductor chip and said dielectric layer.